



## Nanotechnology & Advanced Materials Forum: Electronic Packaging

納米及先進材料技術論壇 - LED電子封裝及散熱方案

### ***CATCHING THE WAVE: Latest Development in Electronic Packaging & Thermal Management for LED***

**Date: 18 March 2011 (Friday)**

**Time: 1:45 – 4:30pm**

Venue: Room 224-225, Hong Kong Convention & Exhibition Centre

Format: Forum, Technology Showcase

Language: English (presentations), Chinese & English (Q&A)

Admission: FREE (Seats are limited. Please register.)

The tremendous progress in semiconductor technology has created a need for effective electronic packaging. One of the bottleneck for LED development has been related to the reliability and performance of electrical packaging and thermal management. For advanced electronics, materials in use today and those becoming available are crucial to ascertain what actions are needed for the industry to compete favorably in the world market .

This symposium will introduce new materials and disruptive processing techniques to address the challenges in electronic packaging and thermal management for LED. The presentations will also assess the existing capability and limitations while outlining the trend of materials and systems development.

Putting the spotlight on the leading-edge material and engineering science, the event offers invaluable insights and outlooks paving the way to the market development of electronic packaging materials. It is a not-to-be missed opportunity for both academia and industry to learn, share, and explore the many possibilities throughout a variety of applications and industry sectors.

Organizer:



納米及先進材料研發院有限公司  
Nano and Advanced Materials Institute Limited

Co-organizer:



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or visit [www.nami.org.hk](http://www.nami.org.hk)



## PROGRAM

- 2:00pm**      **Welcome Remarks**  
Professor Ka Ming NG  
*CEO, Nano and Advanced Materials Institute Ltd*
- 2:15pm**      **Disruptive Packaging Technologies for High Density Microelectronics and 3D IC Integration**  
Professor Ricky SW LEE  
*Professor/Director of Centre for Advanced Microsystems Packaging, Department of Mechanical Engineering, The Hong Kong University of Science & Technology*
- 2:45pm**      **Material and Process Challenges for LED Packaging**  
Dr. Ming LI  
*Senior Technical Manager, ASM Assembly Automation Ltd.*
- 3:15pm**      **Development of Advanced Die Attach Adhesives (DAAs) with Nano-fillers for High Brightness LED (HB-LED)**  
Dr. Tracy CM LIU  
*Assistant Technical Manager, Nano and Advanced Materials Institute Ltd.*
- 3:45pm**      **Reliability Challenges: Electromigration and Thermomigration in Fine-pitch Microelectronic Interconnections and Novel Solder Materials**  
Ms. Margie QQ LI  
*Research Engineer, EPA Centre, Electronic Engineering Department, The City University of Hong Kong*
- 4:00pm**      **Case Study on Graping Phenomenon on Surface Mounted Solder Joints**  
Mr. Matthew TSUI  
*Centre Manager, EPA Centre, Electronic Engineering Department, The City University of Hong Kong*
- 4:15pm**      **Q&A / Refreshment**

*Free Admission.  
Sign Up Now!*



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Yes! I would like to sign up for the Nanotechnology and Advanced Materials Forum on LED Electronic Packaging & Thermal Management on March 18, 2011 at the Hong Kong Convention & Exhibition Centre.

Name: Prof/ Dr/ Mr/ Ms \_\_\_\_\_ Email: \_\_\_\_\_

Company: \_\_\_\_\_ Position: \_\_\_\_\_

Tel/ Mobile: \_\_\_\_\_ Fax: \_\_\_\_\_ Website: \_\_\_\_\_

Address: \_\_\_\_\_

Yes! Sign me up for the NAMI's Consortium complimentary membership. I will enjoy **free conferences and seminars, networking events with industry experts**, and **access to latest technology news and information**. Please send me information regarding:

Business Nature:  Manufacturer  Trading Company  Service Provider  Education  
 Retailer  Financial Services  Trade/ Industrial Organization  Government/ Public Organization

Industry:  Energy & power  Electronics  Medical & pharmaceutical  Textiles  
 Environmental  Metal & machinery  Building & construction  Plastics  
 Chemical  Consulting Services  Others \_\_\_\_\_

Company's Major Products/ Services: \_\_\_\_\_

Areas of Interests:

Solid state lighting  Environmental technology  Metals & metal finishing  
 Lifestyle & healthcare  Sustainable energy  
 Advanced materials for consumer and industrial applications

Topics of your interests at a Future Conference/ Forum: \_\_\_\_\_

I value the following opportunities most:

Networking with industry players  Seeking partners for cooperation for a project  
 Brainstorming new product ideas  Exploring new business/ investment opportunities  
 Obtaining funding support  Understanding latest technology trend and market situation  
 Learning more about technical transfer process and technology commercialization

\*Signature: \_\_\_\_\_

\*Date: \_\_\_\_\_

Please fax this registration form to 2358-8113 or email [karen.wong@nami.org.hk](mailto:karen.wong@nami.org.hk). We look forward to seeing you.

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NAMI's Consortium is open to all interested in nanotechnology and advanced materials.

The Consortium maintains a platform to facilitate **business networking, technology updates, incubation of new ideas** and projects, while **making technology available** to meet the evolving needs of industry. Throughout the year, the Consortium sends out newsletters, conducts regular industry-specific conferences, networking events for researchers, business leaders, industry experts and end-users. The ultimate aim is through this process of cross-fertilization of ideas, local companies will be able to enhance their competitiveness in the world market.